

/ Descriptions

1.2A

ABS/LBF

1.2A Surface Mount Glass Passivated Bridge Rectifier, ABS/LBF thin package.

- / Features

100V~1000V

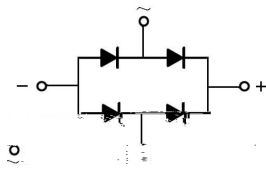
1.2A

Glass Passivated Chip Junction, Reverse Voltage :100 to 1000V,Forward Current: 1.2A,High Surge Current Capability, Designed for Surface Mount Application. Halogen free product.

Applications

General purpose.

Equivalent Circuit

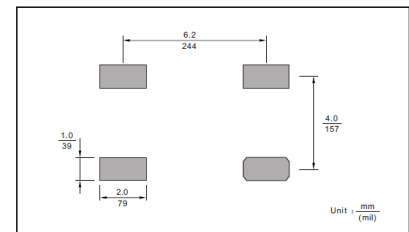


/ Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

The recommended mounting pad size



1 / Marking

See Marking Instructions.

绝对最大额定值(Absolute Maximum Ratings)(Ta=25℃)

Parameter	Symbol	Rating						Unit
		TB1S-12	TB2S-12	TB4S-12	TB6S-12	TB8S-12	TB10S-12	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_c = 125^\circ\text{C}$	I_o	1.2						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	40						A
Typical Junction Capacitance Note1	C_j	18						pF
Typical Thermal Resistance Note2	R_{JA}	70						/W
	R_{JC}	18						/W
Junction Temperature, Storage Temperature Range	T_j, T_{stg}	-55~150						

Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4×1.5"×1.5" 3.81×3.81 cm copper pad.

电气特性(Electrical Characteristics)(Ta=25℃)

Parameter	Symbol	Test Conditions	Rating	Unit
Forward Voltage per element	V_F	$I_F=1.2A$	1.1	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	$T_a=25$	5.0	A
		$T_a=125$	100	A



Electrical Characteristic Curve

Fig.1 Average Rectified Output Current Derating Curve

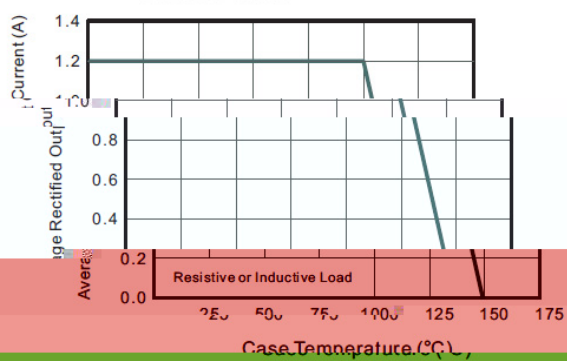


Fig.2 Typical Reverse Characteristics

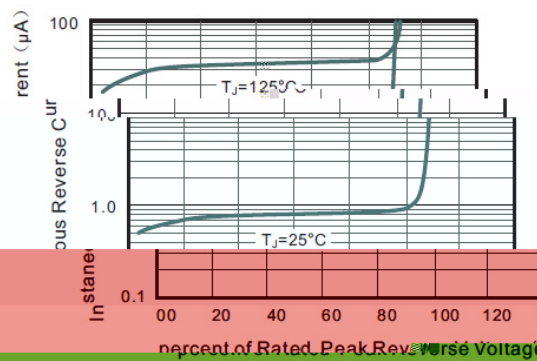


Fig.3 Typical Instantaneous Forward Characteristics

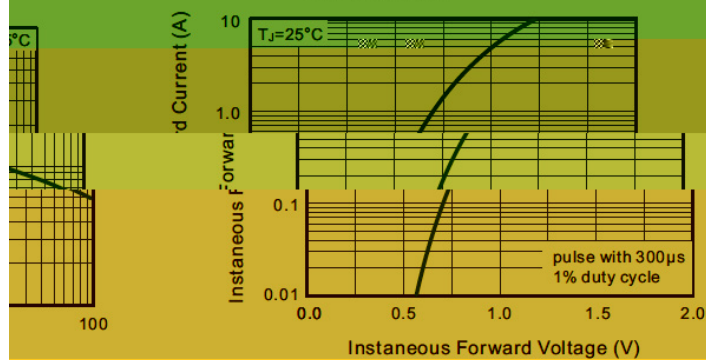


Fig.4 Typical Junction Capacitance

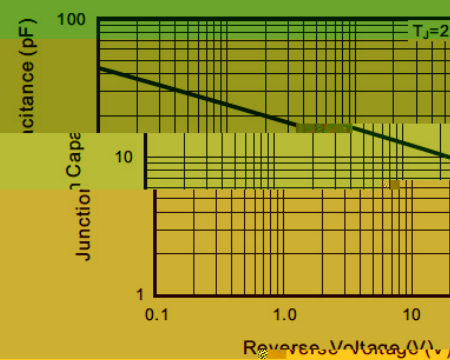
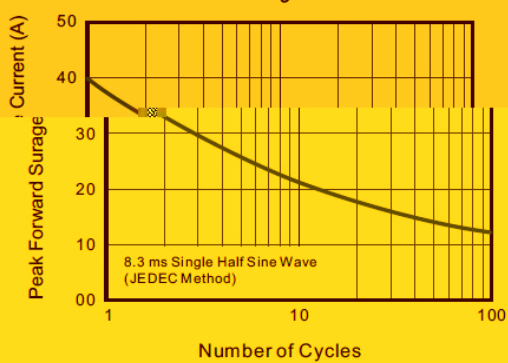
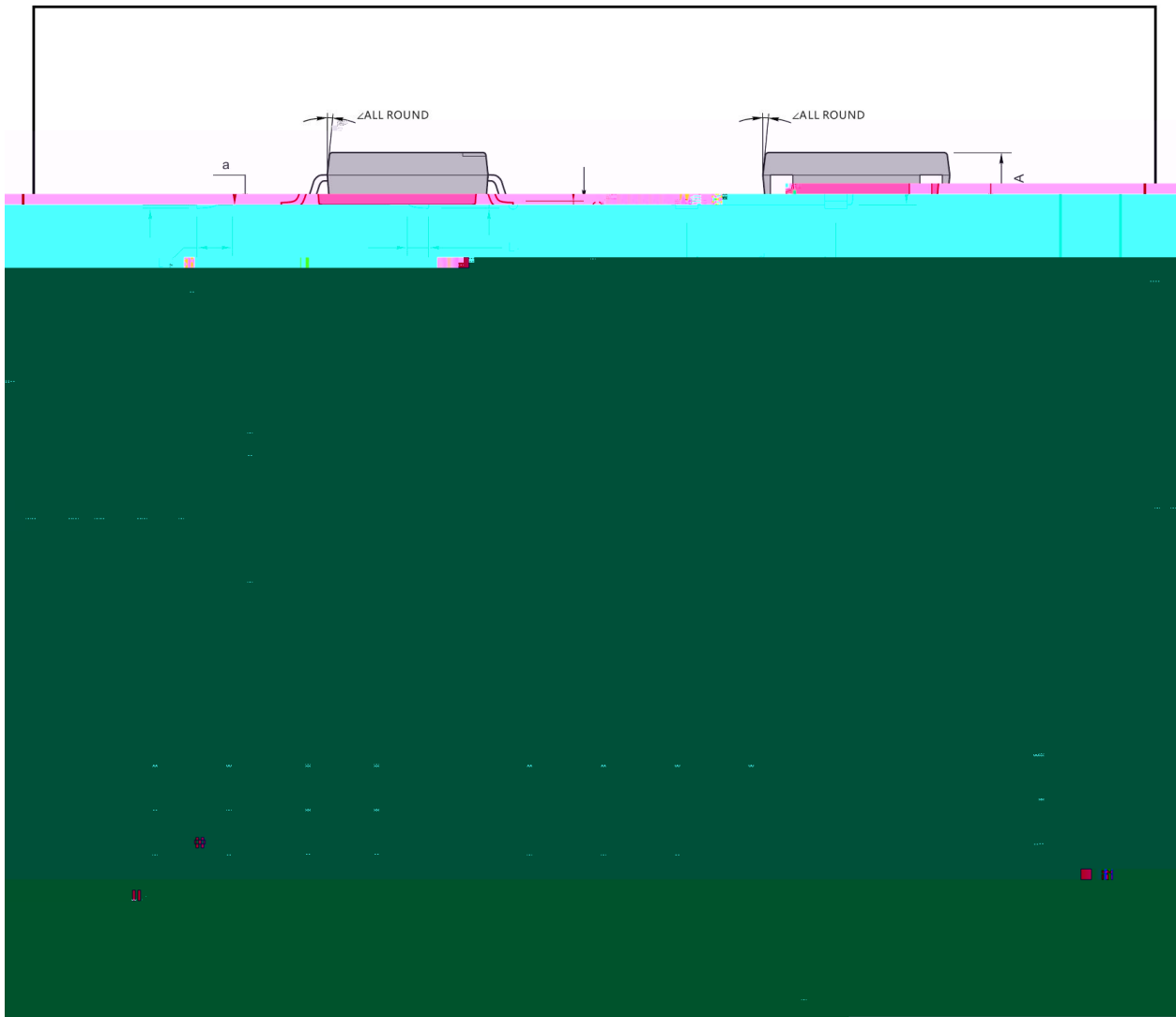


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



/ Package Dimensions

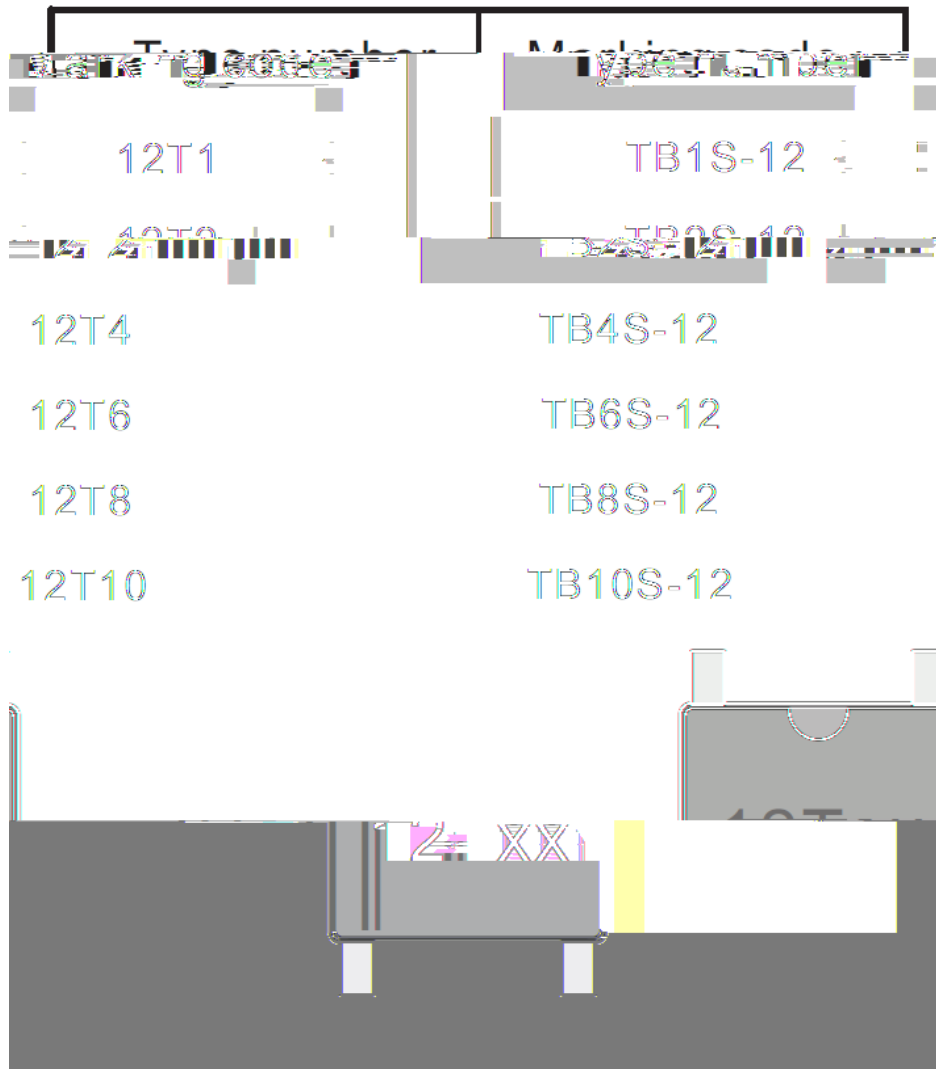
ABS/LBF





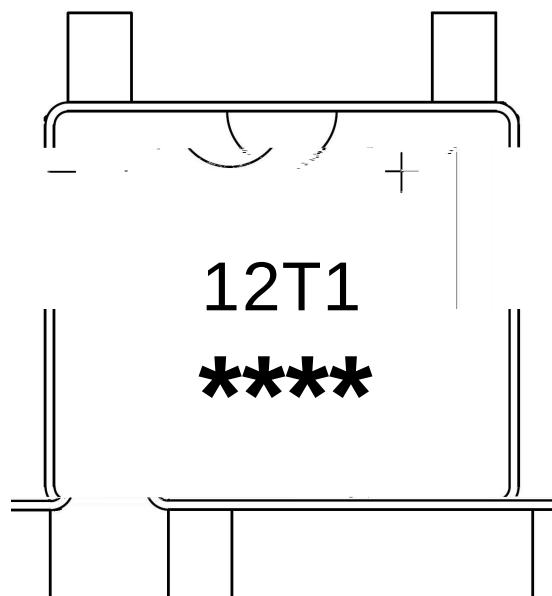
/ Marking Instructions

Marking





/ Marking Instructions



12T1

1 *

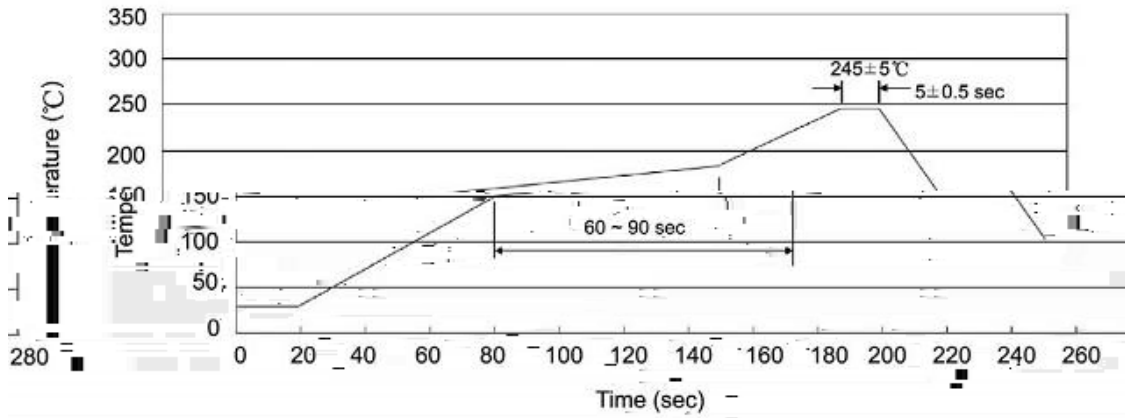
3 *

Note:

12T1 Product Type Code

**** Lot No. Code The 1st * means:YM Code The last 3 * means:little Lot No Code

3. Thermal Characteristics



Note:

- | | | | |
|---|-----------|-------------|---|
| 1 | 150 ~ 180 | 60 ~ 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | 2 ~ 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

4. Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

5. Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
ABS/LBF	5000	2	10000	5	50000	13 ×15	336X336X40	380X335X366

6. Notices